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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ming-Huan Tsai	06/09/2010
Hui Ouyuag	06/09/2010
Chun-Fai Cheng	06/09/2010
Wei-Han Fan	06/09/2010

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	12827344	

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.2205
NAME OF SUBMITTER:	Rachel L.I. Davis

Total Attachments: 3

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PATENT REEL: 028510 FRAME: 0252

Docket No.: 2010-0246 / 24061.1469

Customer No.: 42717

ASSIGNMENT

WHEREAS,	we,
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(1)	Ming-Huan Tsai	of	8F, No. 41, Guangming 6th Road Zhubei City, Hsinchu County 302, Taiwan, R.O.C.
(2)	Hui Ouyang	of	7F, No. 288, Wenping Road Chubei City, Hsinchu County 302, Taiwan, R.O.C.
(3)	Chun-Fai Cheng	of	Fab 12, No. 8, Li-Hsin Road VI, SBIP Hsinchu, Taiwan, R.O.C.
(4)	Wei-Han Fan	of	7F, No. 60, Lane 19, Guan-Hsin Road

have invented certain improvements in

INTEGRATED CIRCUIT DEVICE WITH WELL CONTROLLED

Hsin-Chu City, Taiwan, R.O.C.

SURFACE PROXIMITY AND METHOD OF MANUFACTURING SAME

for which we have executed an application for Letters Patent of the United States of America,

_X	of even date filed herewit	th; and	
	filed on <u>06-30-2010</u> an	nd assigned application nun	iber 12/827, 344; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Ming-Huan Tsai		
Residence Address:	8F, No. 41, Guangming 6th RoadTownshipshan District Zhubei City, Hsinchu County 302, Taiwan, R.O.C.		
Dated: / June	9,2010	Ming Auan Inventor Signature	
***************************************	<u> </u>		
Inventor Name:	Hui Ouyang		
Residence Address:	7F, No. 288, Wenping Road Chubei City, Hsinchu County 3	302, Taiwan, R.O.C.	
Dated: June	9 2010	Inventor Signature	
Inventor Name:	Chun-Fai Cheng		
Residence Address:	Fab 12, No. 8, Li-Hsin Road V. Hsinchu, Taiwan, R.O.C.	I, SBIP	
Dated: June	9 2010	Chun Fai Cheng Inventor Signature	
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Inventor Name:

Wei-Han Fan

Residence Address:

7F, No. 60, Lane 19, Guan-Hsin Road

Hsin-Chu City, Taiwan, R.O.C.

Dated:___

2010'06'09

\$ Wet−Han Fan

Inventor Signature